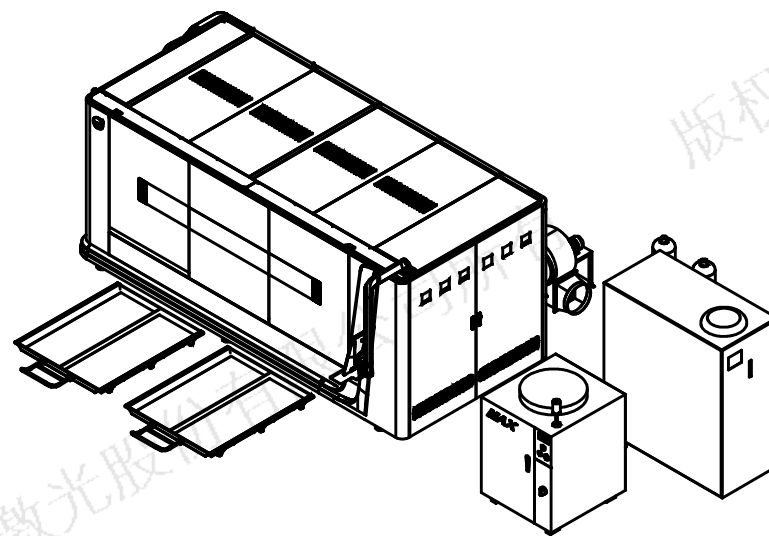
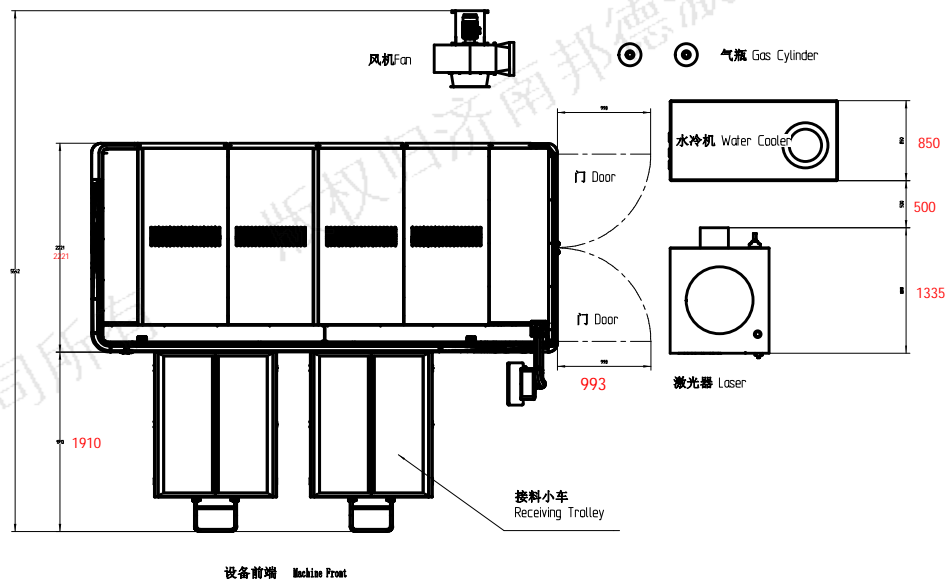
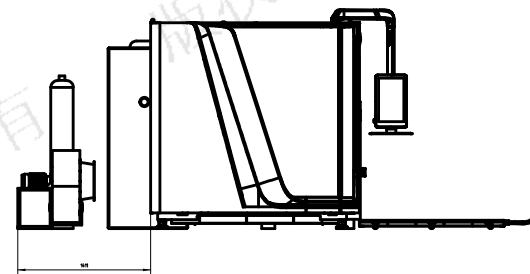
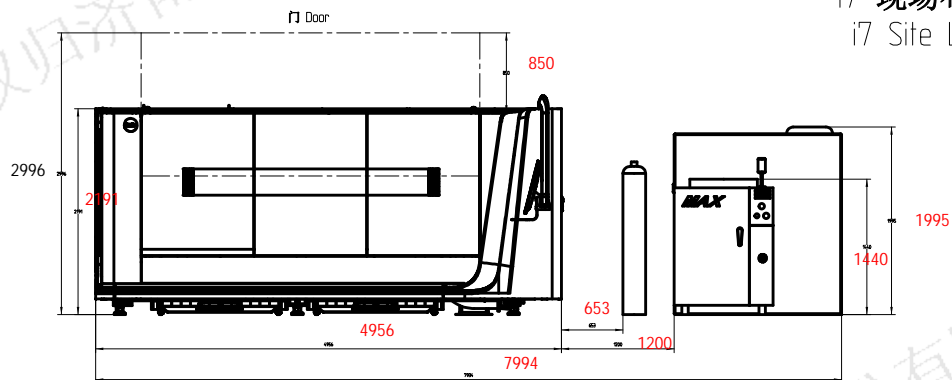


### i7 现场布局图

### i7 Site Layout



#### 1 就位要求

1. 整机四周距障碍物至少1m。
2. 整机应远离震源。
3. 整机就位场地平整度应不大于5mm。
4. 整机接入电压浮动在±5%以内。
5. 若图示区域增设辅助设备请联系邦德确认。
6. 本布置图的设备位置仅做参考，实际摆放可根据现场实际情况而定。

#### 1 Initiation Requirement

1. The whole machine is at least 1m away from obstacles.
2. The whole machine should be away from the earthquake source.
3. The leveling of the whole machine should be less than 5 mm.
4. The whole machine's access voltage fluctuates within (+5%).
5. Please contact Bond for confirmation if additional auxiliary equipment is installed in the illustrated area.
6. The location of the equipment in this layout is for reference only. The actual layout can be determined according to the actual situation of the site.

						图例		济南邦德激光股份有限公司 (Bond Laser Co., Ltd)	
设计	审核	分区	更改内容	日期	年月日	数量	比例	i7 现场布局图 i7 Site layout	
制图	工艺	数量		标注	比例	1:1		D-105-A-10	
审核	日期	共 页		第 页	共 页	共 页	共 页	替代	